

THAPAR INSTITUTE OF ENGINEERING & TECHNOLOGY, PATIALA
(Deemed to be University)
CENTRE FOR INDUSTRIAL LIAISON AND PLACEMENT

Dated: 15.08.2023

CAMPUS INTERVIEWS

1. Name of the Organization: **INFINERA**
(www.infinera.com)

(Profile – Developer & Tester Roles)

Branches of Engineering: BE- CS/ EC/ENC/EEC.

Eligibility Criteria Present CGPA 8.00 and above
No backlog courses at present.

Process of Interviews: Shortlisting based upon details
Online test in TIET Labs
In person two rounds of Interviews at TIET
2. **PPT followed by Online test in TIET will be on ____ September, 2023 at ____**
In person Interviews will be in TIET on ____ September, 2023 ____.
3. **Submit the details & resume to the below TIET Google by 1st September, 2023 by 11.00 AM.**

<https://forms.gle/LSckGQniN5r6nJFU9>
4. CTC ~ 14.00 LPA (Fixed) + 5% (Bonus)

Stipend Rs. 40000 (during internship for each profile)
5. Job location: Bangalore

Head CILP

CC: HCSED/HECED/HEEID - for kind information please

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CAMPUS INTERVIEWS

1. Name of the Organization: **IRES Global**
(<http://www.iresglobal.com>)

Profile enclosed.

Branches of Engineering: B.E.-Chemical Engg.

Eligibility Criteria	10 th , 10+2 / Dip	60%
	Present CGPA	7.50

No backlog at present

Process of Interviews: Short listing based upon your details.
Online Tests
Aptitude Test
Domain Test
Online Interviews

2. Remote Online test will be on ____ August, 2023 at ____

Online interviews will be on ____ August 2023 at ____

3. Submit the details & resume to the below TIET Google by 21st August, 2023 by 11.00 AM.

<https://forms.gle/V5jN7hGU4QrXBKs66>

4. CTC ~ Rs. 6.00 – 7.00 LPA.

5. Job location: New Delhi / Bangalore

Head CILP

CC: HCHED - for kind information please

THAPAR INSTITUTE OF ENGINEERING & TECHNOLOGY, PATIALA
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Dated: 14.08.2023

CAMPUS INTERVIEWS

1. Name of the Organization: **Thorogood**
(www.thorogood.com)

(Profile: Data and Analytics consultant) Enclosed

Branches of Engineering: BE- CHE/CIE/CS/EE/EIC/EC/ENC/EEC/Mech./Mecha
BE-MBA- CS/EC/Mech.
ME-CS/EC/CAD/Structure/Infra.
MCA
M.Sc. Mathematics & Computing

Eligibility Criteria UG - Present CGPA 7.50 & above
PG - Present CGPA 6.50 & above

No Active backlog

Process of Interviews: Shortlisting based upon details
Online test and an interview followed by a full day
assessment center for the shortlisted
candidates. Assessment center will include a case
study, GD and an interview.
Assessment center will be held in Bangalore office.
2. Virtual PPT and remote Online test will be on August /Sep 2023 at ____

Virtual Interviews will be on September, 2023 ____.
3. Submit the details & resume to the below TIET Google by 31st August, 2023 by
11.00 AM.

<https://forms.gle/nPrSnxP99o2B8jCb8>
4. CTC ~ 14,15,400 (incl. a joining bonus of Rs. 1,50,000 payables at the start
of the 2nd year)

Internship stipend – Rs. 35,000/- p.m. (6 months duration)
5. Job location : Bangalore

Head CILP

CC: HCHED/HCED/HCSSED/HECED/HEEID/HMED - for kind information please

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CAMPUS INTERVIEWS

1. Name of the Organization: **Signify**
(www.signify.com)
(Profile - Assistant Development Engineer)

Branches of Engineering: BE- CS/EE/EIC/EC/ENC/EEC.

Eligibility Criteria Present CGPA 7.00 and above
No backlog courses at present.

Process of Interviews: Shortlisting based upon details
Online test
In person two rounds of Interviews at TIET
2. **Virtual PPT & remote Online test will be on ____ September, 2023 at ____**
In person Interviews will be in TIET on ____ September, 2023 ____.
3. **Submit the details & resume to the below TIET Google by 31st August, 2023 by 11.00 AM.**

<https://forms.gle/drcumbTJH729sbT9A>
4. CTC ~ 13.2 LPA + 2.0 L (JB)

Fixed	Variable	Total CTC	Joining Bonus	Stipend
12,00,000	120000	1320000	200000	32000

Stipend to be offered during internship for each profile. 32 K
5. Job location: Bangalore

Head CILP

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CAMPUS INTERVIEWS

1. Name of the Organization: **AIRTEL**
(www.airtel.com)
(Profile enclosed)

Branches of Engineering: BE- CS/EE/EIC/EC/ENC/EEC
M.Sc. - Mathematics & Computing

Eligibility Criteria Present CGPA 7.00 and above
No active backlog

Process of Interviews: Shortlisting based upon details
Online remote test
Online Assessment > 1st Technical Round >
2nd Technical Round > Behavioral Round
2. **Virtual PPT and remote Online test will be on ____ September, 2023 at ____**
Virtual / In person Interviews will be on ____ September, 2023 ____.
3. **Submit the details & resume to the below TIET Google by 4th September, 2023 by 11.00 AM.**

<https://forms.gle/WK1Xy1jRBgNcm15B9>
4. CTC ~ 14.75 LPA (1 LPA – JB & 1 LPA DB included)
5. Job location : PAN India

Head CILP

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CAMPUS INTERVIEWS

1. Name of the Organization: **Tata 1MG**
(www.1mg.com)
(Profile SDE-1)

Branches of Engineering: BE- CS

Eligibility Criteria Present CGPA 8.00 and above
No backlog courses at present.

Process of Interviews: Shortlisting based upon Resume
Online test
In Person two rounds of Interviews in TIET
2. **Remote PPT and remote Online test will be on ____ Sep, 2023 at ____**
In person Interviews will be in TIET on ____ Sep, 2023 ____.
3. **Submit the details & resume to the below TIET Google by 5th September, 2023 by 11.00 AM.**

<https://forms.gle/YcG5p23XcSrL7rK97>
4. CTC ~ Rs. 14.00 LPA (10 fixed+ 4 Performance bonus)
5. Job location : Gurgaon

Head CILP

CC: HCSED/HECED/HEEID - for kind information please